

Announcement / Call for Papers

IMAPS International Conference and Tabletop Exhibition on High Temperature Electronics (HiTEC 2010)

www.imaps.org/hitec

New Mexico - USA
May 11 - 13, 2009

Abstract Deadline Extended: November 20, 2009

HiTEC 2010 continues the tradition of providing the leading biennial conference dedicated to the advancement and dissemination of knowledge of the high temperature electronics industry. Under the organizational sponsorship of the International Microelectronics And Packaging Society (IMAPS), HiTEC 2010 will be the forum for presenting leading high temperature electronics research results and application requirements. It will also be an opportunity to network with colleagues from around the world working to advance high temperature electronics.



Organizing Committee:

Wayne Johnson, Auburn University - johnsr7@auburn.edu
Colin Johnston, Oxford Applied Technology – UK - colin.johnston@materials.ox.ac.uk
F. Patrick McCluskey, University of Maryland - mcclupa@calce.umd.edu
Susan L. Heidger, Air Force Research Laboratory - Susan.Heidger@kirtland.af.mil
Randy Normann, Perma Works, LLC - randy@permaworks.com

Papers are being sought from, but not limited to, the following subjects:

Applications: Geothermal Oil well logging Automotive Military/Aerospace Space Etc.	Device Technologies: Si, SOI SiC Diamond GaN GaAs Contacts Dielectrics	MEMS and Sensors: Vibration Pressure Seismic Etc.	Packaging: Materials Processing Solders/Brazes PC Boards Wire Bonding Flip Chip Insulation Thermal management
Circuits: Analog Digital Power Wireless Optical	Energy Sources: Batteries Nuclear Fuel Cells Etc.	Passives: Resistors Inductors Capacitors Oscillators Connectors	Reliability: Failure mechanisms Experimental and modeling results

Those wishing to present a paper at the HiTEC 2010 Conference must submit a 200-300 word abstract electronically by **November 20, 2009**, using the on-line submittal form at: www.imaps.org/abstracts.htm. All abstracts submitted must represent original, previously unpublished work. **All speakers are required to pay a reduced registration fee.**

Students wishing to present at the High Temperature Electronics Conference must also submit a 200-300 word abstract electronically **no later than November 20, 2009**; you must check the “**YES, I’m a full-time Student**” button at the bottom of the submission page after you enter your abstract text in order to be considered for the student competition award.

If your abstract is selected, a Final Manuscript for publication on the Conference CD-ROM Proceedings will be due on April 2, 2010.

Accepted papers may be considered for publication in the IMAPS Journal of Microelectronics and Electronic Packaging.

If you need assistance with the on-line submission form, please email Jackki Morris-Joyner (jmorris@imaps.org) or call 305-382-8433.